Silicon P-Channel MOS FET

HITACHI

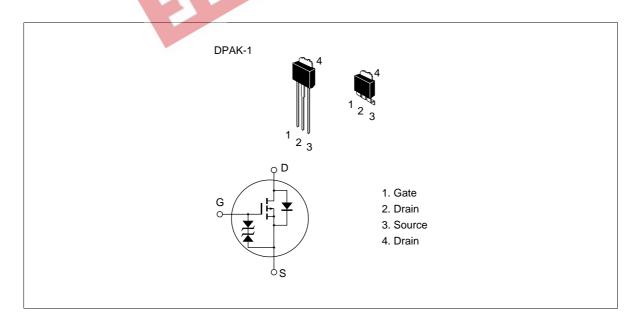
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Tom.cn Suitable for switching regulator and DC-DC converter

Outline





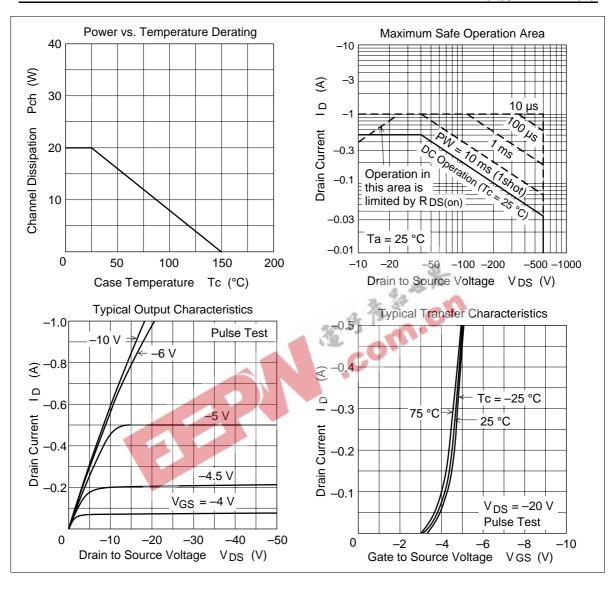
Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

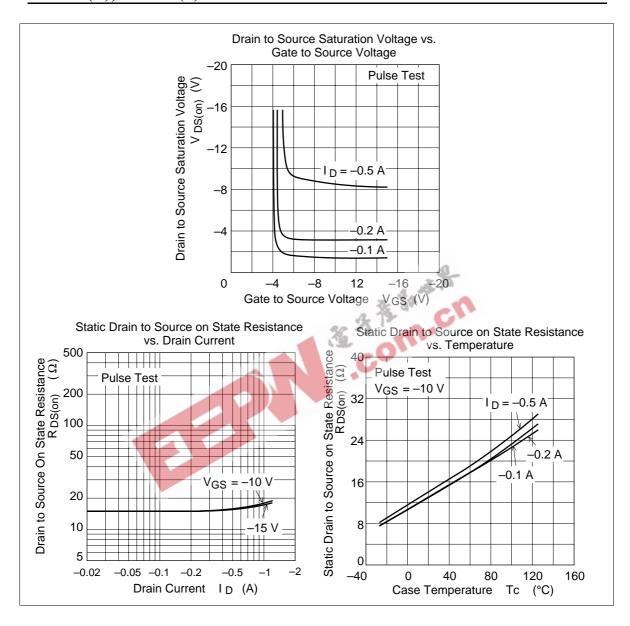
Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	-600	V
Gate to source voltage	V_{GSS}	±15	V
Drain current	I _D	-0.5	Α
Drain peak current	I _{D(pulse)} *1	-1.0	А
Body to drain diode reverse drain current	I _{DR}	-0.5	А
Channel dissipation	Pch*2	20	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

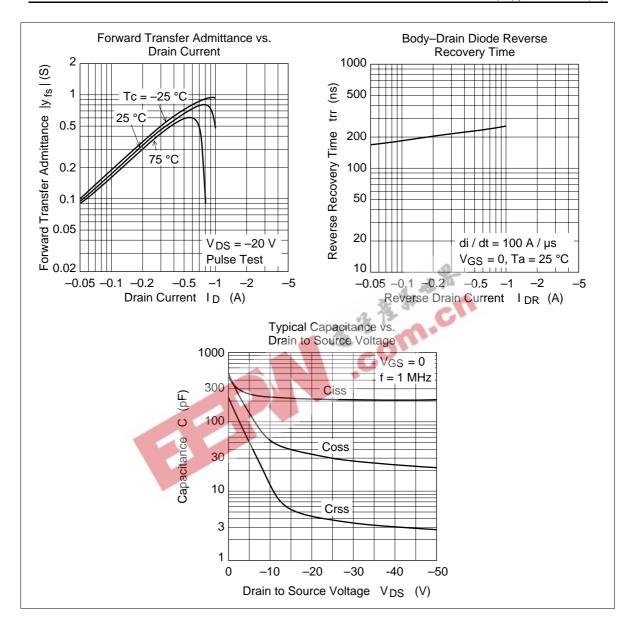
Electrical Characteristics ($Ta = 25^{\circ}C$)

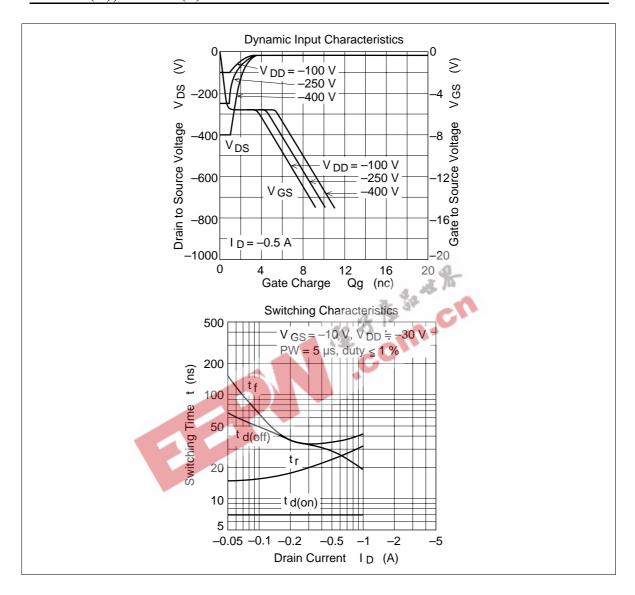
Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%								
2. Value at $T_c = 25^{\circ}C$		2						
					3.15	Ju .		
				. %	30	-W		
2. Value at T_c = 25°C Electrical Characteristics (Ta = 25°C) Item								
Item	Symbol	Min	Тур	Max	Unit	Test conditions		
Drain to source breakdown voltage	$V_{(BR)DSS}$	-600			V	$I_{D} = -10 \text{ mA}, V_{GS} = 0$		
Gate to source breakdown voltage	$V_{(BR)GSS}$	±15	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$		
Gate to source leak current	I _{GSS}	_		±10	μΑ	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0$		
Zero gate voltage drain current	1 _{DSS}	_	_	-100	μΑ	$V_{DS} = -500 \text{ V}, V_{GS} = 0$		
Gate to source cutoff voltage	$V_{\text{GS(off)}}$	-2.0	_	-4.0	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$		
Static drain to source on state resistance	$R_{\scriptscriptstyle DS(on)}$	_	15	25	Ω	$I_D = -0.3 \text{ A}, V_{GS} = -10 \text{ V}^{*1}$		
Forward transfer admittance	y _{fs}	0.3	0.45	_	S	$I_D = -0.3 \text{ A}, V_{DS} = -20 \text{ V}^{*1}$		
Input capacitance	Ciss	_	220	_	pF	$V_{DS} = -10 \text{ V}, V_{GS} = 0,$		
Output capacitance	Coss	_	55	_	pF	f = 1 MHz		
Reverse transfer capacitance	Crss	_	13	_	pF			
Turn-on delay time	$t_{d(on)}$	_	7	_	ns	$I_D = -0.3 \text{ A}, V_{GS} = -10 \text{ V},$		
Rise time	t _r	_	20	_	ns	$R_L = 100 \Omega$		
Turn-off delay time	$t_{\text{d(off)}}$	_	35	_	ns	_		
Fall time	t _f	_	35	_	ns			
Body to drain diode forward voltage	V_{DF}	_	-0.85	_	V	$I_F = -0.5 \text{ A}, V_{GS} = 0$		
Body to drain diode reverse recovery time	t _{rr}	_	230	_	ns	$I_F = -0.5 \text{ A}, V_{GS} = 0,$ $di_F/dt = 50 \text{ A}/\mu\text{s}$		

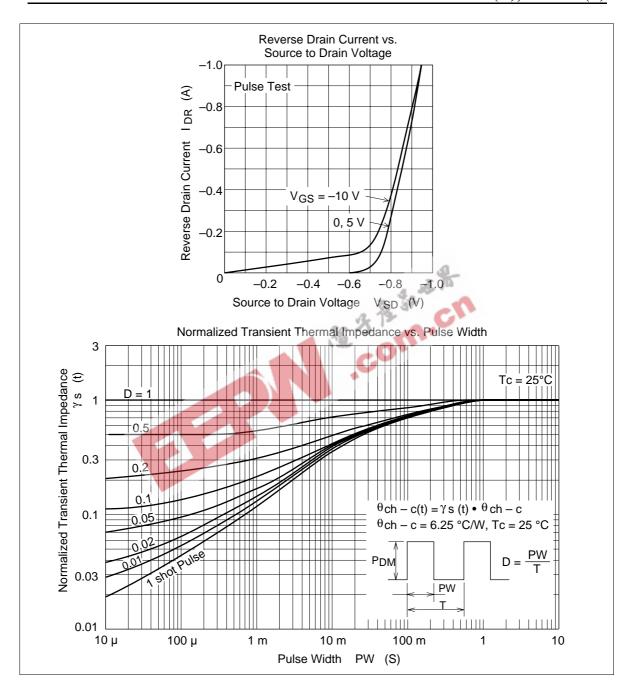
Note: 1. Pulse test

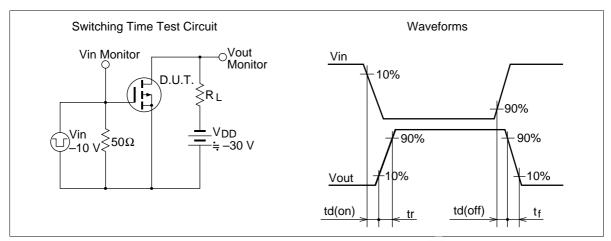








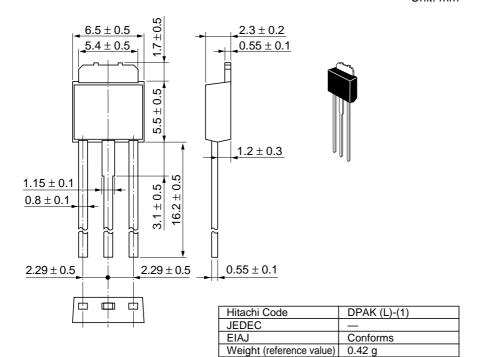








Unit: mm



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Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223 Hitachi Europe GmbH Electronic components Group Dornacher Stra§e 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0

Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd. Electronic Components Group.

Whitebrook Park

Lower Cookham Road

Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd

Taipei Branch Office 3F, Hung Kuo Building. No.167 Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218 Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

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